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## TABLE OF CONTENTS

<b>Contents No.</b>	<b>Page</b>
Certificate, Declaration and Copy right transfer	ii-iv
Acknowledgement	v-vi
Table of Contents	vii-x
List of figures	xi-xv
List of Tables	xvi
List of symbols	xvii-xx
Abstract	xxi-xxiii
<b>1. Introduction</b>	<b>1-10</b>
1.1 Boiling curve and Regime of boiling	1
1.2 Nucleate boiling: the preferred regime	4
1.3 Implication of surface modification or texturing in boiling heat transfer enhancement	5
1.4 Motivation	5
1.5 Thesis structure	7
<b>2. State of the Art</b>	<b>9-30</b>
2.1 Historical background	9
2.2 Fabrication Methods (micro/nano textured surfaces)	12
2.2.1 Micromaching and Surface polishing	12
2.2.2.1 Physical coating methods	14
2.2.2.2. Spray coatings	14
2.2.2.3 Bonding with epoxy	15

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2.2.3 Vapour deposition techniques	16
2.2.4 Chemical/Electrochemical methods	19-23
2.2.4.1 Electrochemical deposition (ECD)	21
2.2.4.2 Electrophoretic deposition (EPD)	23
2.2.5 MEMS/NEMS Technologies	23
2.3 Wettability effects on boiling heat transfer and bubble dynamics	25
2.4 Summary and research gap	26
2.5 Aim and objectives	29
<b>3. Surface preparation and characterization</b>	<b>31-58</b>
3.1 Coating method and materials	31
3.1.1 Pre-treatment and surface polishing	36
3.1.2 Hybrid nanofluid preparation	36
3.2 Surface characterization	40-46
3.2.1.1 TiO <sub>2</sub> -SiO <sub>2</sub> coated surface	41
3.2.1.2 TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	44
3.2.1.3 SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	47
3.2.2 Energy Dispersive Spectroscopy (EDS) analysis	47
3.2.3 Coating thickness	49
3.2.4 Surface roughness	51
3.2.5. Contact angle measurements/wettability analysis	53
3.3. Summary	58
<b>4. Experimental setup &amp; procedure</b>	<b>59-72</b>
4.1 Description of pool boiling apparatus	59
4.2 Experimental procedure	64

---

4.3 Calculation of Heat flux and other performance parameters	67
4.4 Uncertainty analysis	69
4.5 Validation of experimental setup	70
4.6 Summary	71
<b>5. Pool boiling characteristics of water on textured surfaces</b>	<b>73-98</b>
5.1 Pool boiling performance curve	73-79
5.1.1 Effect of TiO <sub>2</sub> -SiO <sub>2</sub> coating	74
5.1.2 Effect of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coating	75
5.1.3 Effect of SiO <sub>2</sub> - Al <sub>2</sub> O <sub>3</sub> coatings	77
5.2 Effects on ONB temperature	79
5.3 Effects on heat transfer coefficient	82-92
5.3.1 Effect of TiO <sub>2</sub> -SiO <sub>2</sub> coating	82
5.3.2 Effect of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coating	86
5.3.3 Effect of SiO <sub>2</sub> - Al <sub>2</sub> O <sub>3</sub> coatings	89
5.4 Wettability and roughness effects	93
5.5 Effects of coating thickness	95
5.6 Summary	97
<b>6. Study of bubble visualization and dynamics</b>	<b>99-110</b>
6.1 Description of visualization procedure	99
6.2 Bubble growth and visualization	100
6.3 Effect of surface roughness	102
6.4 Bubble dynamics	104
6.4.1 Bubble departure diameter	104
6.4.2 Bubble departure frequency	107

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Summary	110
<b>7. Conclusions and future work scope</b>	<b>111-116</b>
7.1 Conclusions	112
7.2 Novelty of the thesis work	114
7.3 Keys benefits if apply this study in engineering applications	115
7.4 scope for future work	115
<b>References</b>	<b>117-134</b>
<b>List of publications</b>	<b>135</b>

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## LIST OF FIGURES

<b>Fig. No.</b>	<b>Name</b>	<b>Page No.</b>
Fig. 1.1	Typical pool boiling curve for saturated water at atmospheric pressure	3
Fig. 2.1	Categorization of micro/nano textured preparation methods and its associated techniques.	12
Fig. 3.1	Schematic illustration of electrophoretic deposition technique	32
Fig. 3.2	Sequence of various activities which was followed in the surface coating by EPD method.	37
Fig. 3.3	Photograph of bath sonicator (Model: GT-1730QTS, Frequency: 33/40 kHz, Power: 100 W).	37
Fig. 3.4	Photograph of Probe sonicator	38
Fig. 3.5	Illustration of two-step method for hybrid nanofluid preparation	38
Fig. 3.6	Zeta potential distribution of hybrid nanofluids	39
Fig. 3.7	FESEM image of polished (bare) Cu surface	42
Fig. 3.8	Surface morphology (FESEM image) of TiO <sub>2</sub> -SiO <sub>2</sub> coated surface at two different magnification	43
Fig. 3.9	Surface morphology (FESEM image) of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface (CS2) at 20k, and 100k magnification	45
Fig. 3.10	Surface morphology (FESEM image) of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface (CS3) at two different magnification	46

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Fig. 3.11	EDS spectrum of TiO <sub>2</sub> -SiO <sub>2</sub> coated (CS1-5) surface.	48
Fig. 3.12	EDS spectrum of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated (CS2-5) surface	48
Fig. 3.13	EDS spectrum of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated (CS3-5) surface	48
Fig. 3.14	Measurement of coating thickness (cross section image FESEM) of TiO <sub>2</sub> -SiO <sub>2</sub> coated surface	49
Fig. 3.15	Measurement of coating thickness (cross section image FESEM) of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	50
Fig. 3.16	Measurement of coating thickness (cross section image FESEM) of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	50
Fig. 3.17	Plot of coating thickness against the coating time	51
Fig. 3.18	Surface roughness profile of polished Cu (Bare) surface	52
Fig. 3.19	Surface roughness profile of coated surface	52
Fig. 3.20	Pictorial view of contact angle measurement facility	54
Fig. 3.21	Sessile drop image and contact angle measurement of a polished Cu (bare) surface	54
Fig. 3.22	Sessile drop image and contact angle measurement of TiO <sub>2</sub> -SiO <sub>2</sub> coated surface	55
Fig. 3.23	Sessile drop image and contact angle measurement of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	55
Fig. 3.24	Sessile drop image and contact angle measurement of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated surface	56
Fig. 4.1	Schematic diagram of pool boiling experimental setup	60
Fig. 4.2	Sample holder made of PTFE Teflon	61

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Fig. 4.3	Schematic diagram of copper heating block with cartridge heater and sample holder arrangement	61
Fig. 4.4	Image of cartridge heater	62
Fig. 4.5	Image of K-type thermocouple	62
Fig. 4.6	Data acquisition system for temperature measurements	63
Fig. 4.7	Temperature distribution within copper heating block	63
Fig. 4.8	Pictorial view of an auxiliary heater	64
Fig. 4.9	Pool boiling test facility	65
Fig. 4.10	Plot of temperature profile at different heat flux which are measured by thermocouple in copper heating block	68
Fig. 4.11	Comparison of pool boiling data of bare surface with Rohsenow's model (1952) and experimental data	71
Fig. 5.1	Pool boiling performance curve of polished Cu and TiO <sub>2</sub> -SiO <sub>2</sub> coated surface	74
Fig. 5.2	Pool boiling performance curve of polished Cu and TiO <sub>2</sub> - Al <sub>2</sub> O <sub>3</sub> coated surface	76
Fig. 5.3	Pool boiling performance curve of SiO <sub>2</sub> - Al <sub>2</sub> O <sub>3</sub> coated surfaces	78
Fig. 5.4	ONB points marked with the circle on the boiling curve of TiO <sub>2</sub> -SiO <sub>2</sub> coated samples.	79
Fig. 5.5	Comparison of wall superheat temperature when bubble formation initiated on the surface	80
Fig. 5.6	Plot of heat transfer coefficient against the heat flux of TiO <sub>2</sub> -SiO <sub>2</sub> coated and Polished Cu surfaces	83

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Fig. 5.7	Variation in HTC enhancement at different heat flux on TiO <sub>2</sub> -SiO <sub>2</sub> coated samples	84
Fig. 5.8	Plot of maximum enhancement in HTC and corresponding heat flux of TiO <sub>2</sub> -SiO <sub>2</sub> coated samples	84
Fig. 5.9	Plot of experimental heat transfer coefficient against the heat flux of TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated and Polished Cu surfaces	86
Fig. 5.10	Illustration of HTC enhancement on TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated samples against the supplied heat fluxes	87
Fig. 5.11	Illustration of Max. Enhancement in HTC and corresponding heat flux on TiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated samples	88
Fig. 5.12	Variation of experimental heat transfer coefficient against the heat flux of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated and Polished Cu surfaces	89
Fig. 5.13	Variation in HTC enhancement at different heat flux on SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated samples	90
Fig. 5.14	Plot of maximum enhancement in HTC and corresponding heat flux of SiO <sub>2</sub> -Al <sub>2</sub> O <sub>3</sub> coated samples	91
Fig. 5.15	Illustration of liquid-vapour interface	92
Fig. 5.16	Plot of free energy related function $f(\theta)$ against the contact angle ( $\theta$ )	94
Fig. 6.1	Comparison of bubble generation (qualitative) on bare surface (hydrophilic) top row (a, b, c, & d), and composite surface CS2-5 (hydrophobic) bottom row (e, f, g, & h) at different heat flux.	101
Fig. 6.2	Illustration of bubble formation and departure phenomena on bare (hydrophilic) surfaces	101

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Fig. 6.3	Illustration of bubble formation and departure phenomena on coated (hydrophobic) surface CS2-10	102
Fig. 6.4	Effects of roughness on bubble formation and their behaviour at three different heat flux condition	103
Fig. 6.5	Bubble departure diameter as function of Jacob Number (Ja) for $\text{TiO}_2$ - $\text{SiO}_2$ textured surfaces	105
Fig. 6.6	Bubble departure diameter as function of Jacob Number (Ja) for $\text{TiO}_2$ - $\text{Al}_2\text{O}_3$ textured surfaces	106
Fig. 6.7	Plot of bubble departure diameter against the Jacob Number (Ja) for $\text{SiO}_2$ - $\text{Al}_2\text{O}_3$ textured surfaces	106
Fig. 6.8	Variation of bubble departure frequency against the Jacob Number (Ja) on $\text{TiO}_2$ - $\text{SiO}_2$ textured surfaces	108
Fig. 6.9	Variation of bubble departure frequency on $\text{TiO}_2$ - $\text{Al}_2\text{O}_3$ textured surfaces	108
Fig. 6.10	Variation of bubble departure frequency at different Jacob Number (Ja) on $\text{SiO}_2$ - $\text{Al}_2\text{O}_3$ coated textured surfaces	109

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## LIST OF TABLES

<b>Table. No.</b>	<b>Title</b>	<b>Page No.</b>
Table 3.1	Potential advantages and disadvantages of EPD and other conventional technique	33-35
Table 3.2	Materials (nanoparticle) details	35
Table 3.3	Details of micro/nano composite coating parameters	41
Table 3.4	Arithmetic mean value of Surface roughness (Ra)	53
Table 3.5	Results of contact angle measurements on bare and coated surfaces	56
Table 4.1	Specifications of various Devices/Elements of experimental setup	66
Table 4.2	Uncertainty of measured parameters	69
Table 4.3	Estimated uncertainty of derived parameters	70
Table 5.1	Summarized result of optimum coating layer thickness and corresponding surface properties as well	96

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## LIST OF SYMBOLS

### **Nomenclature**

$h$	Heat transfer coefficient (W/m <sup>2</sup> K)
$h_c$	Planck constant
$h_{fg}$	Latent heat of vaporization (J/kg)
$k$	Boltzmann constant
$k_{cu}$	Thermal conductivity of copper (W/m-K)
$c_{pf}$	Specific heat of fluid at liquid phase (J/kg-K)
$D$	Bubble diameter (m)
$f_b$	Bubble frequency (Hz)
$q''$	Heat flux (kW/m <sup>2</sup> )
$T$	Temperature (° C)
$\Delta T$	( $T_w - T_{sat}$ ) Wall superheat temperature (K)
$n_a$	Active nucleation site density (sites/m <sup>2</sup> )
$T_1$	Temperature of thermocouple location first (° C)
$T_2$	Temperature of thermocouple location second (°C)
$T_3$	Temperature of thermocouple location third (°C)
$v$	Volume (cm <sup>3</sup> )
SiO <sub>2</sub>	Silica dioxide
TiO <sub>2</sub>	Titanium dioxide
Al <sub>2</sub> O <sub>3</sub>	Aluminum oxide
CS	Coated surface

***Greek symbols***

$\sigma$	Surface tension of liquid (N/m)
$\rho_v$	Vapor density(g/cm <sup>3</sup> )
$\rho_l$	Liquid density (g/cm <sup>3</sup> )
$\theta$	Contact angle (°)
$\Delta$	Difference
$\phi$	Volume concentration

***Subscripts***

<i>bf</i>	Base fluid
<i>np</i>	Nanoparticle
<i>d</i>	Departure
<i>f</i>	fluid
<i>w</i>	wall
<i>sat</i>	saturation

**Abbreviations**

CHF	Critical heat flux
MaCE	Metal assisted chemical etching
LbL	Layer -by-layer
EPD	Electrophoretic deposition
ECD	Electrochemical deposition
CVD	Chemical vapour deposition
LPCVD	Low pressure chemical vapour deposition
PECVD	Plasma-enhanced chemical vapour deposition

MOCVD	Metal organic chemical vapour deposition
HFCVD	Hot filament chemical vapour deposition
ALD	Atomic layer deposition
DRIE	Deep reactive ion etching
BDA	Break down anodization
BIT	Boiling inception temperatures
PVD	Physical vapour deposition
GLAD	Glancing angle deposition
EBPVD	Electron beam physical vapour deposition
ONB	Onset of nucleate boiling
HTC	Heat transfer coefficient
BHTC	Boiling heat transfer coefficient
NBHT	Nucleate boiling heat transfer
DI	Deionised water
HF	Hydrofluoric
CCD	Charge-coupled device
CNT	Carbon nanotubes
ENM	Engineered nanomaterials
AFM	Atomic force microscopy
SEM	Scanning electron microscopy
FESEM	Field emission scanning electron microscopy
EDX	Energy dispersive X-ray spectroscopy
EDM	Electric discharge machining
NWs	Nanowires
RMS	Root mean square

CNTs	Carbon nanotubes
HFE	Hydrofluoroether
AAO	Anodised alumina oxide
PPA	Porous alumina
PTFE	Polytetrafluoroethylene
ITO	Indium tin oxide
SWCNT	Single-walled carbon nanotubes
MWCNT	Multi-walled carbon nanotubes
MEMS	Microelectromechanical systems
MPF	Micro-pin-fin